

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2	"20040180549"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:33
2	BRS	0	semiconductor adj (wafer substrate) with (grinding thinning) and resin and (electrode electrodes) and adhesive with support and (bump bumps) and (through?hole via)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:35
3	BRS	84	semiconductor adj (wafer substrate) with (grinding thinning) and resin and (electrode electrodes) and (bump bumps) and (through?hole via)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:53
4	BRS	177	semiconductor adj (wafer substrate) with (grinding thinning) and resin same (electrode electrodes)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:46
5	BRS	127	semiconductor adj (wafer substrate) with (grinding thinning) and resin with (electrode electrodes)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:47
6	BRS	4	semiconductor adj (wafer substrate) with (grinding thinning) and resin with (electrode electrodes) and resin with spin?coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:48
7	BRS	4	semiconductor adj (wafer substrate) with (grinding thinning) and resin same (electrode electrodes) and resin with spin?coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:48
8	BRS	4	semiconductor adj (wafer substrate) with (grinding thinning) and resin and (electrode electrodes) and resin with spin?coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:48
9	BRS	102	semiconductor adj (wafer substrate) and resin and (electrode electrodes) and resin with spin?coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:48
10	BRS	46	semiconductor adj (wafer substrate) and resin with (electrode electrodes) and resin with spin?coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:48

	Type	Hits	Search Text	DBs	Time Stamp
11	BRS	13	semiconductor adj (wafer substrate) with (grinding thinning) and resin with (press pressing pressed) and (electrode electrodes) and (bump bumps) and (through?hole via)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:54
12	BRS	13	semiconductor adj (wafer substrate) with (grinding thinning) and resin with (press pressing pressed) and (electrode electrodes) and (bump bumps)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:54
13	BRS	173	semiconductor adj (wafer substrate) and resin with (press pressing pressed) and (electrode electrodes) and (bump bumps)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:54
14	BRS	120	semiconductor adj (wafer substrate) and resin with (press pressing pressed) and (electrode electrodes) and (bump bumps) and (through?hole via)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:54
15	BRS	120	semiconductor adj (wafer substrate) and resin with (press pressing pressed) and (electrode electrodes) and (bump bumps) and (through?hole via)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 21:54
16	BRS	2476	semiconductor adj (wafer substrate) and resin with (thickness height)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 15:45
17	BRS	577	semiconductor adj (wafer substrate) and support with metal and resin	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 15:42
18	BRS	83	S16 and S17	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 15:42
19	BRS	0	semiconductor adj (wafer substrate) and first adj area same second adj are	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 15:45

	Type	Hits	Search Text	DBs	Time Stamp
20	BRS	1471	semiconductor adj (wafer substrate) and first adj area same second adj area	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:45
21	BRS	119	semiconductor adj (wafer substrate) and first adj area same second adj area and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:47
22	BRS	62	semiconductor adj wafer and first adj area same second adj area and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:48
23	BRS	880	semiconductor adj wafer and peripheral with (metal resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:53
24	BRS	46	semiconductor adj wafer with (grinding thinning) and peripheral with (metal resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:49
25	BRS	47	semiconductor adj wafer and peripheral adj area with (metal resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:59
26	BRS	183	semiconductor adj wafer same peripheral adj area	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 15:59
27	BRS	15	semiconductor adj wafer same peripheral adj area and peripheral with (height thick thicker)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 16:04
28	BRS	980	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) with (metal resin height thick thicker)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 16:05
29	BRS	533	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (metal resin height thick thicker)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 16:05
30	BRS	79	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (metal resin height thick thicker) and resin and electrodes	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/05 16:10

	Type	Hits	Search Text	DBs	Time Stamp
31	BRS	76	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thickness resin height thick thicker) and resin and electrodes	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 16:10
32	BRS	72	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thickness support height thick thicker) and resin and electrodes	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 16:24
33	BRS	82	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thicker)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/05 16:25
34	BRS	11	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thicker) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:51
35	BRS	4160	semiconductor adj wafer and circuit adj board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:23
36	BRS	14	semiconductor adj wafer and circuit adj board and chip adj resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:26
37	BRS	330	semiconductor adj wafer and circuit adj board and side with electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:29
38	BRS	42	semiconductor adj wafer and chip adj resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:26
39	BRS	191	semiconductor adj wafer and circuit adj board and side near3 electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:32
40	BRS	2	"6005474".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/07 22:32
41	BRS	0	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thicker) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:50

	Type	Hits	Search Text	DBs	Time Stamp
42	BRS	0	semiconductor adj (wafer substrate) same (peripheral periphery) and (peripheral periphery) near5 (thicker) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:50
43	BRS	4	semiconductor adj wafer same (peripheral periphery) and (peripheral periphery) near5 (thicker) and resin same (peripheral periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:57
44	BRS	20	semiconductor adj wafer same (peripheral periphery) and (thicker) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:04
45	BRS	339	semiconductor adj wafer same (peripheral periphery) and resin same (peripheral periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:57
46	BRS	191	semiconductor adj wafer same (peripheral periphery) and resin with (peripheral periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:57
47	BRS	93	semiconductor adj wafer same (peripheral periphery) and resin near5 (peripheral periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 16:57
48	BRS	268	semiconductor adj wafer same (peripheral periphery) and (thicker thick thickness) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:05
49	BRS	166	semiconductor adj wafer same (peripheral periphery) and (thicker thick thickness) with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:05
50	BRS	116	semiconductor adj wafer same (peripheral periphery) and (thicker thick thickness) near5 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:05
51	BRS	93	semiconductor adj wafer same (peripheral periphery) and (thicker thick thickness) near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:05
52	BRS	78	semiconductor adj wafer same (peripheral periphery) and (thicker thick thickness) near2 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 17:06

	Type	Hits	Search Text	DBs	Time Stamp
53	BRS	2755	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42
54	BRS	1029	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42
55	BRS	365	438/110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42
56	BRS	369	438/111.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42
57	BRS	811	438/113.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42
58	BRS	1313	438/118.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 20:42